MSE 4754 - Electronic Packaging Assembly
LECTURE SCHEDULE

DATES FOR CLASSES	TOPIC	FACULTY
(Mondays) 12:05 – 12:50 PM Instruction Center 107		
January 9th	SOP Introduction	Rao Tummala (ECE)
January 16th	OFFICIAL SCHOOL HOLIDAY	
January 23th	Chip Assembly - 1	Dan Baldwin (ME)
January 30th	Chip Assembly - 2	Dan Baldwin (ME)
February 6th	NO LECTURE	
February 13th	Materials and encapsulation-1	C.P.Wong (MSE)
February 20th	Materials and encapsulation-2	C.P.Wong (MSE)
February 27th	Thermo-Mechanical modeling-1	Suresh Sitaraman (ME)
March 6th	Thermo-Mechanical modeling-2	Suresh Sitaraman (ME)
March 13th	MID TERM	
March 20th - 24th	SPRING BREAK	
March 27th	Reliability Analysis	Jiamin Qu (ME)
April 3rd	Moire Interferometry	Jiamin Qu (ME)
April 10th	Thermal management	Y. Joshi (ME)
April 17th	Electrical test	David Keezer (ECE)
April 24th	Electrical test	David Keezer (ECE)
May 1st - 5th	**FINAL REPORT AND PRESENTATION**	

LABORATORY EXPERIMENTS SCHEDULE

DATES OF LAB SESSIONS	TOPICS THAT WILL BE COVERED IN EACH WEEK / LOCATION	FACULTY, TA INVOLVED	MATERIAL TO COVER
Jan 10th- 14th	**Distribution of Handbooks, Group, Finalization of laboratory schedules**.	Dr. Kim	
Jan 18th – 21st	**No Lab.**		
Jan 24th - 28th	**Assembly:** Chip Qualifications of PB08-02, PB08-04, FA10-02 - Microscope -DAGE shear force measurements **383 MaRC**	Dr. Kim	
Jan 31st - Feb 4th	**Assembly:** Flip Chip Assembly - Set-up BTU oven for reflow temperature - Assemble chips - X-ray check **383 MaRC**	Dr. Kim	
Feb 7th –11th	**Underfil dispensing of the samples** - Curing of the samples **383 MaRC**	Dr. Kim	
Feb 14th - 18th	**Underfill material characterization** - TGA and DSC measurements **378 Love Mfg Blgd.**	Dr. Kim, TA	
Feb 21st-25th	**Underfill material characterization** - DMA, TMA and Rheology measurements **378 Love Mfg Blgd.**	Dr. Kim, TA	
Feb 28th – Mar 4th	**Thermo Mechanical Modeling** Ansys model development for FA10 **2104 MRDC**	Dr. Kim, TA	
Mar 7th – 11th	**Thermo Mechanical Modeling** Ansys model development for FA10 **2104 MRDC**	Dr. Kim, TA	
Mar 14th - 18th	**MID SEMESTER NO LAB SESSION**		
Mar 21st – 25th	**SPRING BREAK, NO LAB SESSIONS**		
Mar 28th – Apr 1st	**Ultrasonic scanning** **383 MaRC**	Dr. Kim	
Apr 4th – 8th	**Ultrasonic scanning** **383 MaRC**	Dr. Kim,	
Apr 11th – 15th	**Section Polishing. Visual investigation.** **383 MaRC**	Dr. Kim	
Apr 18th – 22nd	**Section Polishing. Visual investigation.** **383 MaRC**	Dr. Kim	
Apr 25th – 29th	**383 MaRC**	Dr. Kim	
May 2nd – 6th	**Project Presentation and Final Report submission** **301 MaRC**	All Faculty	